

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor chip module comprising:

~~— a chip mounting member having opposite first and second surfaces, a set of first circuit traces, and a plurality of plated through holes that extend through said first and second surfaces and that are connected to said first circuit traces;~~

~~— a first semiconductor chip having a pad mounting surface with a plurality of contact pads provided thereon;~~

~~— a first dielectric tape member for bonding adhesively said first semiconductor chip on said chip mounting member;~~

~~— a first conductor unit for connecting electrically said contact pads of said first semiconductor chip and said first circuit traces; and~~

~~— a plurality of solder balls disposed on one of said first and second surfaces of said chip mounting member, each of said solder balls being aligned with and being connected to a respective one of said plated through holes in said chip mounting member.~~

A semiconductor chip module comprising:

~~a chip-mounting member having opposite first and second surfaces, a set of [first] circuit traces disposed on said first surface of said chip-mounting member, and a plurality of plated through holes that extend through said first and second surfaces and that are connected to said [first] circuit traces, said chip-mounting member being formed with a first opening that extends through said first and second surfaces thereof;~~

~~a [first] semiconductor chip having a pad mounting surface with a plurality of contact pads provided thereon;~~

~~a [first] dielectric tape member for bonding adhesively said pad mounting surface of said [first] semiconductor chip on said second surface of said chip-mounting member, said dielectric tape member being formed with a second opening that is registered with said first opening for access to said contact pads of said semiconductor chip;~~

~~a [first] conductor unit including a plurality of wires for connecting electrically said contact pads of said [first] semiconductor chip and said [first] circuit traces on said first surface~~

of said chip-mounting member; and

a plurality of solder balls disposed on one of said first and second surfaces of said chip-mounting member, each of said solder balls being aligned with and being connected to a respective one of said plated through holes in said chip-mounting member.

2-19. (cancelled)

20. (new) The semiconductor chip module as claimed in Claim 1, wherein said [first] semiconductor chip has a peripheral portion that is provided with an epoxy resin layer to strengthen bonding of said [first] semiconductor chip with [the other one of said first and second surfaces] said second surface of said chip-mounting member.

21. (new) The semiconductor chip module as claimed in Claim 1, wherein said [first] semiconductor chip has a heat dissipating surface that is opposite to said pad mounting surface and that has a heat dissipating plate secured thereon.

22. (new) The semiconductor chip module as claimed in Claim 1, further comprising an encapsulation layer provided on said [one of said first and second surfaces] first surface of said chip-mounting member to enclose said pad mounting surface of said [first] semiconductor chip and said [first] conductor unit.

23. (new) A semiconductor chip module stack, comprising:

upper and lower semiconductor chip modules, each including

a chip-mounting member having opposite first and second surfaces, a set of circuit traces disposed on said first surface of said chip-mounting member, and a plurality of plated through holes that extend through said first and second surfaces and that are connected to said circuit traces, said chip-mounting member being formed with a first opening that extends through said first and second surfaces thereof,

a semiconductor chip having a pad mounting surface with a plurality of contact pads provided thereon,

a dielectric tape member for bonding adhesively said pad mounting surface of said semiconductor chip on said second surface of said chip-mounting member, said dielectric tape member being formed with a second opening that is registered with said first opening for access to said contact pads of said semiconductor chip,

a conductor unit including a plurality of wires for connecting electrically said contact pads of said semiconductor chip and said circuit traces on said first surface of said chip-mounting member, and

a plurality of solder balls disposed on one of said first and second surfaces of said chip-mounting member, each of said solder balls being aligned with and being connected to a respective one of said plated through holes in said chip-mounting member;

wherein said upper and lower semiconductor chip modules are interconnected by said solder balls on said chip-mounting member of one of said upper and lower semiconductor chip modules and said plated through holes in said chip-mounting member of the other one of said upper and lower semiconductor chip modules.

24. (new) The semiconductor chip module stack as claimed in Claim 23, wherein said solder balls of said upper semiconductor chip module are provided on said first surface of said chip-mounting member of said upper semiconductor module, and said solder balls of said lower semiconductor chip module are provided on said second surface of said chip-mounting member of said lower semiconductor module,

said solder balls of said upper semiconductor chip module being aligned with and being connected to said plated through holes in said chip-mounting member of said lower semiconductor chip module at said first surface of said chip-mounting member of said lower semiconductor chip module.